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Applicant: Chun Hsien Lin et al. § Docket No.: 2002.0992 / 24061.495
Serial No.: 10/723,236 §
Filed: November 26, 2003 § Examiner: Lee D. Wilson
For: An Advanced Process Control § Art Unit: 2812
Approach for CU Interconnect §
Wiring Sheet Resistance § Conf. No.: 9176
Control §

TRANSMITTAL

Mail Stop: Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application.

1. Response to Office Action dated September 22, 2005;
2. Information Disclosure Statement Form 1449;
3. Check in the amount of \$180 (for IDS fee);
4. This transmittal, in duplicate; and
5. Return postcard.

The Director is authorized to charge any deficiency fees or credit any overpayments associated with this communication to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

Wing Y Mok
Agent for Applicants
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Date: 12/21/05

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CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on <u>October 17, 2005</u> .	
<u>December 21, 2005</u>	
<u>Bonnie Boyle</u> Bonnie Boyle	